3D Packaging and Integration Japan TC Chapter

Japan Standards Spring Meetings 2026
Monday, March 9, 2026
Room 1, SEMI Japan, Tokyo, Japan/ Official Virtual TC Chapter Meeting (Hybrid)
2:00 PM – 5:00 PM JST

AGENDA

1 Welcome/Call to Order

1.1 Introductions

1.2 Required Elements (Membership Requirements, Antitrust and Intellectual Property Reminders, and Effective Meeting Guidelines)

1.3 Agenda Review

2 Review of Previous Meeting Minutes

3 Technical Committee Award

4 Ballot Review

4.1 Doc.#7398, New Standard: Test Method for Wafer Bond Strength Measurement by Double-Cantilever Beam

5 Liaison Report

5.1 JRSC Report

5.2 GCS Report

5.3 North America TC Chapter

5.4 Taiwan TC Chapter

6 Staff Report

7 Subcommittee & Task Force Reports

7.1 3DS IC Bonded Layer Inspection Metrology Task Force

7.2 Wafer Bond Strength Measurement by Double-cantilever Beam Task Force

7.3 3D Packaging & Integration 5-Year Review Task Force

7.4 3D Packaging & Integration Steering Group

8 Old Business

8.1 Project Period Review

8.2 5-Year Review

9 New Business

10 Action Item Review

10.1 Open Action Items

Item #	*Assigned to*	*Details*
3DP&I_20250519-03	5-Year Review TF	To prepare Line Item/ Major Revision SNARFs for SEMI G74 and G87.
3DP&I_20250519-04	5-Year Review TF	To prepare Line Item Revision SNARFs for SEMI G82 and G95.
3DP&I_20251006-01	Wafer Bond Strength Measurement by Double-cantilever Beam TF	To submit the Letter Ballot for Doc.#7398 in Cycle 1 or 2, 2026.
3DP&I_20251006-02	SEMI Staff	To send the ballot review results of Doc.#7359, 7360, 7361 to the ISC A&R SC for procedural review.
3DP&I_20251006-03	Wafer Bonding Pressure TF	To have a TF kick off meeting and reconsider the TF name.

10.2 New Action Items

Item #	*Assigned to*	*Details*

11 Next Meeting and Adjournment